TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

## 2SK3498

# DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain-source ON resistance: RDS (ON) =  $4.0 \Omega$  (typ.)

• High forward transfer admittance:  $|Y_{fs}| = 0.6 \text{ S (typ.)}$ 

• Low leakage current:  $IDSS = 100 \mu A (max) (VDS = 400 V)$ 

• Enhancement-model:  $V_{th} = 2.0 \text{ to } 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

#### Maximum Ratings (Tc = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	400	V	
Drain-gate voltage (Ro	$_{\rm SS} = 20 \; \rm k\Omega)$	V <sub>DGR</sub>	400	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1	) I <sub>D</sub>	1	Α	
	Pulse (Note 1	) I <sub>DP</sub>	3		
Drain power dissipatio	n	PD	20	W	
Single pulse avalanche	e energy (Note 2	E <sub>AS</sub>	113	mJ	
Avalanche current		I <sub>AR</sub>	1	Α	
Repetitive avalanche	energy (Note 3	B) E <sub>AR</sub>	2	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature r	ange	T <sub>stg</sub>	-55 to150	°C	

#### **Thermal Characteristics**

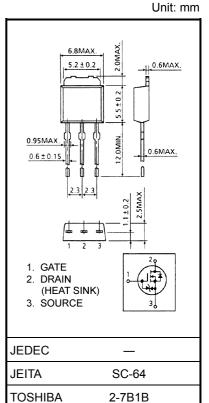
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	6.25	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	125	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

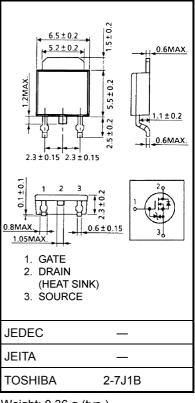
Note 2:  $V_{DD} = 90 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 183 mH,  $R_G = 25 \Omega$ ,  $I_{AR} = 1 \text{ A}$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.



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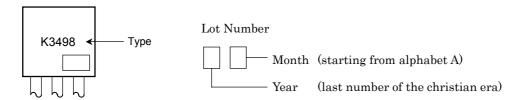
## **Electrical Characteristics (Tc = 25°C)**

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain-source brea	akdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-OFF cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	450	_	_	V
Gate threshold vo	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 A	_	4.2	5.5	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.5 A	0.3	0.6	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	145	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	35	_	
Output capacitance		C <sub>oss</sub>		_	80	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ 0 V $V_{GS}$ 0 V $V_{DD} = 0.5 \text{ A}$ $V_{DD} = 200 \text{ V}$ Duty ≤ 1%, $t_W = 10 \text{ μs}$	_	14	_	
	Turn-ON time	t <sub>on</sub>		_	56	_	ns
	Fall time	t <sub>f</sub>		_	26	_	115
	Turn-OFF time	t <sub>off</sub>		_	75	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	5.7	_	nC
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 320 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}$		3.0		
Gate-drain ("miller") charge		Q <sub>gd</sub>			2.7	_	

## **Source-Drain Ratings and Characteristics (Tc = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	$I_{DR}$	_	_	_	1	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	3	Α
Forward voltage (diode)	$V_{DSF}$	I <sub>DR</sub> = 1 A, V <sub>GS</sub> = 0 V	_	_	-1.7	٧
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 1 \text{ A}, V_{GS} = 0 \text{ V},$	_	650	_	ns
Reverse recovery charge	Qrr	dI <sub>DR</sub> /dt = 100 A/μs		14.6		μС

### Marking



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